



# 8B (NE)  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814  
Examiner: Dana FARAHANI

In Re PATENT APPLICATION Of:

Applicant(s): Yoshinori SHIZUNO

Serial No.: 09/705,729

Filed: November 6, 2000

For: SEMICONDUCTOR DEVICE AND METHOD  
OF MANUFACTURING THE SAME

Docket No.: OKI-267

AMENDMENT  
AFTER FINAL

January 7, 2003

Assistant Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on October 8, 2002, please amend  
the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A semiconductor device, comprising:  
a semiconductor chip;  
metal thin wires respectively connected to electrodes on said semiconductor  
chip;  
a wiring board having an opening for accommodating said semiconductor chip  
and being electrically connected to said semiconductor chip by said metal thin wires;  
a heat spreader having a flat principle surface, and having said semiconductor  
chip and said wiring board provided over the flat principal surface;

TECHNOLOGY CENTER 2800

JAN - 9 2003

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ENCLOSURE  
FEE ENCLOSED: \$750.00  
Pl as charg any further  
fee to our Deposit Account  
No. 18-0002